

(19) World Intellectual Property Organization International Bureau



(43) International Publication Date
14 July 2005 (14.07.2005)

PCT

(10) International Publication Number
WO 2005/064642 A1

(51) International Patent Classification⁷: **H01L 21/00**

(21) International Application Number:
PCT/JP2004/019681

(22) International Filing Date:
22 December 2004 (22.12.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2003-431346 25 December 2003 (25.12.2003) JP
2003-432480 26 December 2003 (26.12.2003) JP

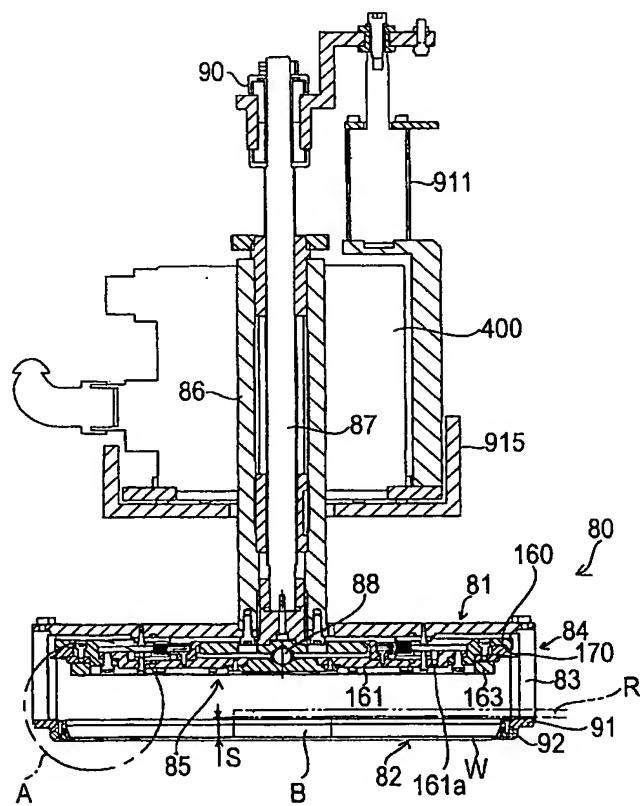
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(54) Title: **SUBSTRATE HOLDING APPARATUS, SUBSTRATE HOLDING METHOD, AND SUBSTRATE PROCESSING APPARATUS**



(57) Abstract: A substrate holding apparatus can meet the request for a smaller-sized compact apparatus while ensuring a sufficient immersion depth of a substrate in a processing liquid. The substrate holding apparatus includes: a substrate holder (84) for supporting a substrate (W) by bringing a peripheral portion of a surface of the substrate (W) into contact with a first sealing member (92); and a substrate pressing section (85) for lowering relative to the substrate holder (84) so as to press the substrate (W) held by the substrate holder (84) downward, thereby bringing the first sealing member (92) into pressure contact with the substrate (W); wherein the substrate pressing section (85) is provided with a second ring-shaped sealing member (170) which makes pressure contact with an upper surface of a ring-shaped holding section of the substrate holder (84), thereby sealing the peripheral region of the substrate pressing section (85).

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(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

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